Developed by Utilizing Core Technologies (Gravure Printing, Lamination, and Coating) accumulated as World’s Largest Comprehensive Printing Company, Each of 9 high quality cover tape products in our lineup is suitable for Electronic Components and Electronic Devices.

**Application**

Cover Tape for Embossed Carrier Tape to be used for Transportation of Electronic Devices

**Features**

- **a. Stable Peeling Strength**
  - Sealable in wide temperature range
  - Less change of Peeling Strength by aging
  - Applicable to High Speed Mounting

- **b. Applicable to Multiple Types of Carrier Tape Materials**
  - Can be used with multiple carrier tapes; PS, PC, and APET.

- **c. Stable Conductivity**
  - Stable Conductivity in low temperature environment.

**Manufacturing Capacity / Environment**

High Productivity, Stable Product Performance, and Safety.
- All DNP Cover Tapes are manufactured in the largest film converting plant in DNP Group that also manufactures packages for food and medical products.

**Capability of Analysing and Measurering**

Equipped Measurement Tools
- Peeling Strength / Peeling-Charged Eletrostatic potential /
- Surface Resistance / Haze / Transmittance

DNP R&D Center enables Highly Accurate Analysis at the atomic level.
DNP Cover Tape Lineup

1. LT-6P25  • Normal Type / Suitable for PP Carrier / High Transparency
2. C-300    • Anti-Static Type / Suitable for PP Carrier / High Transparency
3. C-800    • Conductive Type / Suitable for PS Carrier / Low Temp Seal ability / Peeling Strength Stability / High Transparency
4. F4DR    • Conductive Type / Applicable for Multiple Carrier (PS, PC, A-PET) / Transparency
5. F4DK    • Conductive Type / Suitable for PS & PC Carrier / High Transparency
6. FIT-D    • Conductive Type / Suitable for PS & PC Carrier / Ultra Transparency
7. F4IZ    • Anti-Static Type / Suitable for PS Carrier / High Transparency
8. F4DR SP  • Conductive Type / Applicable for Multiple Carrier (PS, PC, A-PET) / Ultra Transparency
9. F4DK SP  • Conductive Type / Applicable for multiple Carrier (PS, PC, A-PET) / Ultra Transparency
Layer Structure

- **C-800**
  - Anti-Static PET (16um)
  - Inner PE Layer (35um)
  - Conductive Heat Seal layer (1um)
  - 52 um

- **F4DR**
  - Anti-Static PET (12um)
  - Inner PE Layer (30um)
  - Conductive Heat Seal Layer (1um)
  - 48 um

- **F4DK**
  - Anti-Static PET (12um)
  - Inner PE Layer (30um)
  - Conductive Heat seal layer (1um)
  - 48 um

- **FIT-D**
  - Anti-Static PET (30mic)
  - Inner PE Layer (30um)
  - Conductive Heat seal layer (1um)
  - 48 um
# Physical Properties

<table>
<thead>
<tr>
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<th>Measurement Unit</th>
<th>Measurement Standard /Method</th>
<th>C-800</th>
<th>F4DR</th>
<th>F4DK</th>
<th>FIT-D</th>
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<td>Thickness</td>
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<td>Elongation</td>
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The properties above are just typical and representative values measured at DNP and are not to be guaranteed.